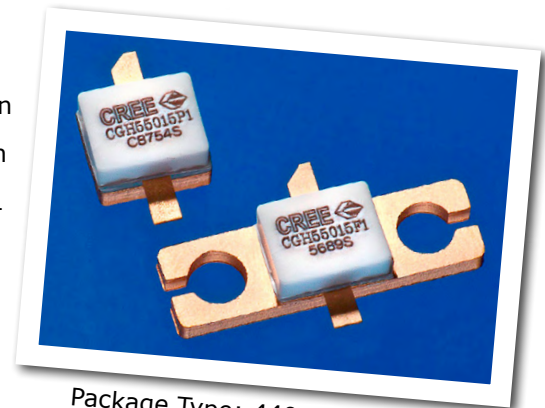


CGH55015F1 / CGH55015P1

15 W, 5500-5800 MHz, GaN HEMT for WiMAX

Cree's CGH55015F1/CGH55015P1 is a gallium nitride (GaN) high electron mobility transistor (HEMT) designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGH55015F1/CGH55015P1 ideal for 5.5-5.8 GHz WiMAX and linear amplifier applications. The transistor is available in both screw-down, flange and solder-down, pill packages. Based on appropriate external match adjustment, the CGH55015F1/CGH55015P1 is suitable for 4.9 - 5.5 GHz applications as well.



Package Type: 440196 & 440166
PN: CGH55015P1 & CGH55015F1

Typical Performance 5.5-5.8GHz ($T_c = 25^\circ\text{C}$)

| Parameter | 5.50 GHz | 5.65 GHz | 5.80 GHz | Units |
|--|----------|----------|----------|-------|
| Small Signal Gain | 10.7 | 11.0 | 10.7 | dB |
| EVM at $P_{AVE} = 23$ dBm | 1.9 | 1.8 | 2.0 | % |
| EVM at $P_{AVE} = 33$ dBm | 1.5 | 1.5 | 1.7 | % |
| Drain Efficiency at $P_{AVE} = 33$ dBm | 25 | 25 | 25 | % |
| Input Return Loss | 11.5 | 14.5 | 10.5 | dB |

Note:

Measured in the CGH55015-TB amplifier circuit, under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5 ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

Features

- 5.5 - 5.8 GHz Operation
- 15 W Peak Power Capability
- >10.5 dB Small Signal Gain
- 2 W $P_{AVE} < 2.0$ % EVM
- 25 % Efficiency at 2 W Average Power
- Designed for WiMAX Fixed Access 802.16-2004 OFDM Applications
- Designed for Multi-carrier DOCSIS Applications



Large Signal Models Available for SiC & GaN



Absolute Maximum Ratings (not simultaneous) at 25 °C Case Temperature

| Parameter | Symbol | Rating | Units | Conditions |
|---|-----------------|-----------|-------|------------|
| Drain-Source Voltage | V_{DSS} | 84 | Volts | 25 °C |
| Gate-to-Source Voltage | V_{GS} | -10, +2 | Volts | 25 °C |
| Power Dissipation | P_{DISS} | 7 | Watts | |
| Storage Temperature | T_{STG} | -65, +150 | °C | |
| Operating Junction Temperature | T_J | 225 | °C | |
| Maximum Forward Gate Current | I_{GMAX} | 4.0 | mA | 25 °C |
| Maximum Drain Current ¹ | I_{DMAX} | 1.5 | A | 25 °C |
| Soldering Temperature ² | T_S | 245 | °C | |
| Screw Torque | τ | 60 | in-oz | |
| Thermal Resistance, Junction to Case ³ | $R_{\theta JC}$ | 8.0 | °C/W | 85 °C |
| Case Operating Temperature ³ | T_C | -40, +150 | °C | 30 seconds |

Note:

¹ Current limit for long term, reliable operation.

² Refer to the Application Note on soldering at www.cree.com/products/wireless_appnotes.asp

³ Measured for the CGH55015 at $P_{DISS} = 7W$.

Electrical Characteristics ($T_c = 25^\circ C$)

| Characteristics | Symbol | Min. | Typ. | Max. | Units | Conditions |
|--|--------------|------|------|--------|----------|--|
| DC Characteristics¹ | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | -3.8 | -3.0 | -2.3 | V_{DC} | $V_{DS} = 10 V, I_D = 3.6 mA$ |
| Gate Quiescent Voltage | $V_{GS(Q)}$ | - | -2.7 | - | V_{DC} | $V_{DS} = 28 V, I_D = 115 mA$ |
| Saturated Drain Current | I_{DS} | 2.9 | 3.5 | - | A | $V_{DS} = 6.0 V, V_{GS} = 2.0 V$ |
| Drain-Source Breakdown Voltage | V_{BR} | 120 | - | - | V_{DC} | $V_{GS} = -8 V, I_D = 3.6 mA$ |
| RF Characteristics^{2,3} ($T_c = 25^\circ C, F_0 = 5.65 GHz$ unless otherwise noted) | | | | | | |
| Small Signal Gain | G_{SS} | 8.5 | 11.0 | - | dB | $V_{DD} = 28 V, I_{DQ} = 115 mA$ |
| Drain Efficiency ⁴ | η | 20.6 | 25 | - | % | $V_{DD} = 28 V, I_{DQ} = 115 mA, P_{AVE} = 2.0 W$ |
| Error Vector Magnitude | EVM | - | 2.0 | 2.5 | % | $V_{DD} = 28 V, I_{DQ} = 115 mA, P_{AVE} = 2.0 W$ |
| Output Mismatch Stress | VSWR | - | - | 10 : 1 | Ψ | No damage at all phase angles, $V_{DD} = 28 V, I_{DQ} = 115 mA,$ $P_{AVE} = 2.0 W$ |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{GS} | - | 4.5 | - | pF | $V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz$ |
| Output Capacitance | C_{DS} | - | 1.3 | - | pF | $V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz$ |
| Feedback Capacitance | C_{GD} | - | 0.2 | - | pF | $V_{DS} = 28 V, V_{gs} = -8 V, f = 1 MHz$ |

Notes:

¹ Measured on wafer prior to packaging.

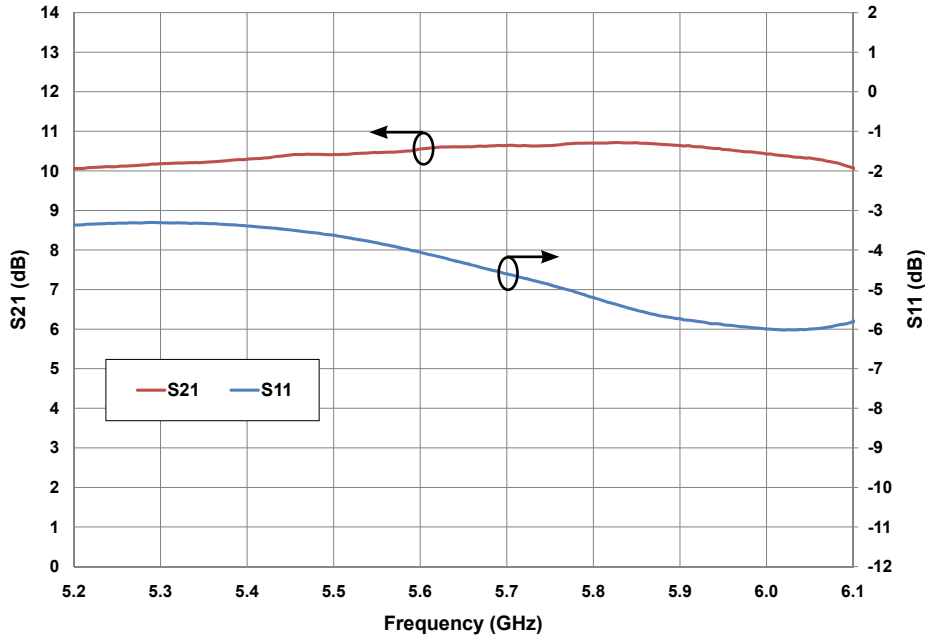
² Measured in the CGH55015-TB test fixture.

³ Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, 5 ms Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

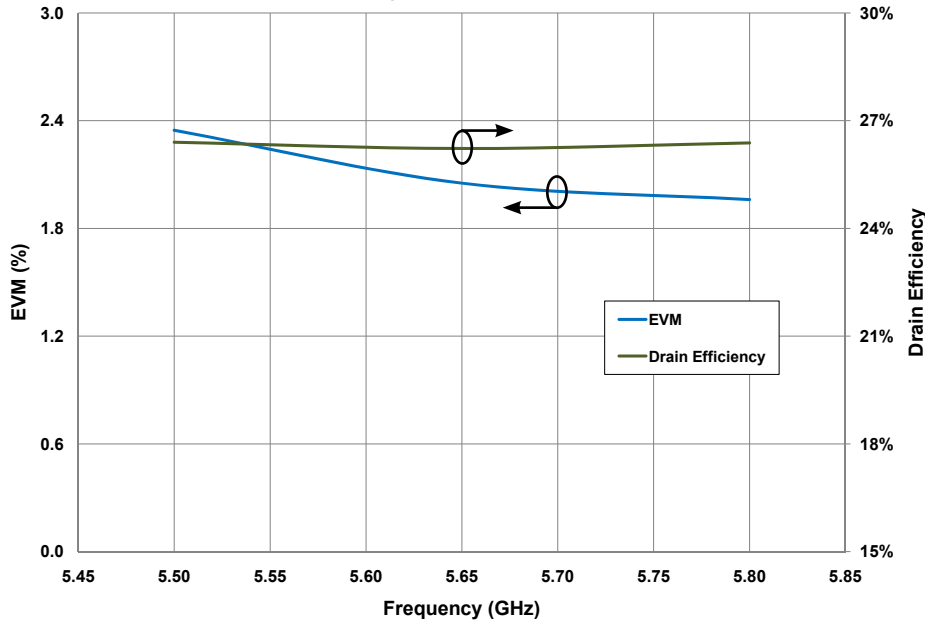
⁴ Drain Efficiency = P_{OUT} / P_{DC} .

Typical WiMAX Performance

Small Signal S-Parameters vs Frequency of CGH55015 in the CGH55015-TB
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 115\text{ mA}$



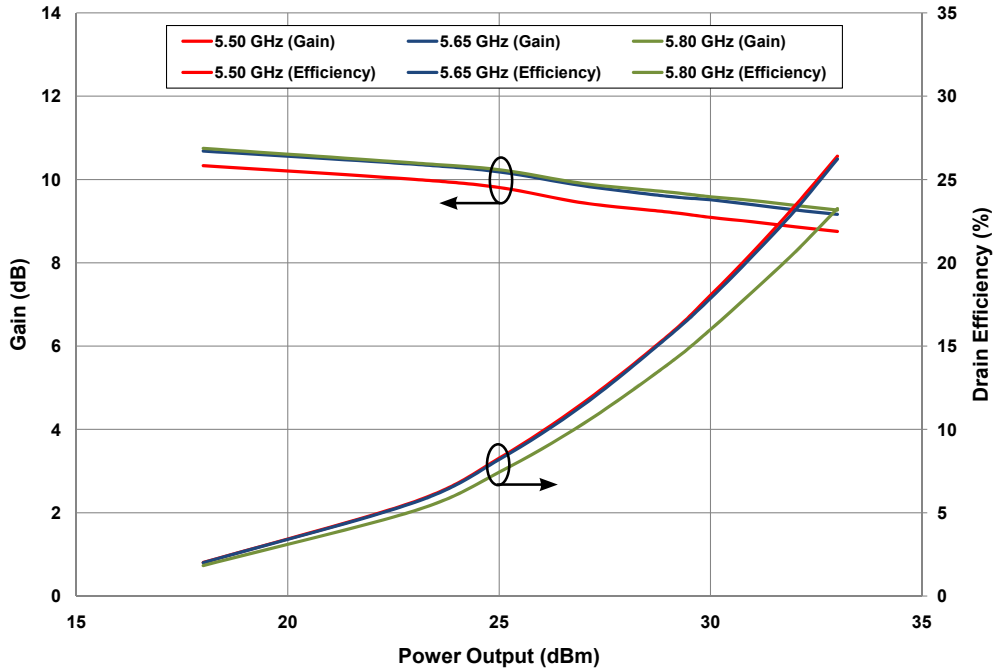
EVM and Efficiency of CGH55015 vs. Frequency in the CGH55015-TB
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 115\text{ mA}$, $P_{OUT} = 2.5\text{ W}$



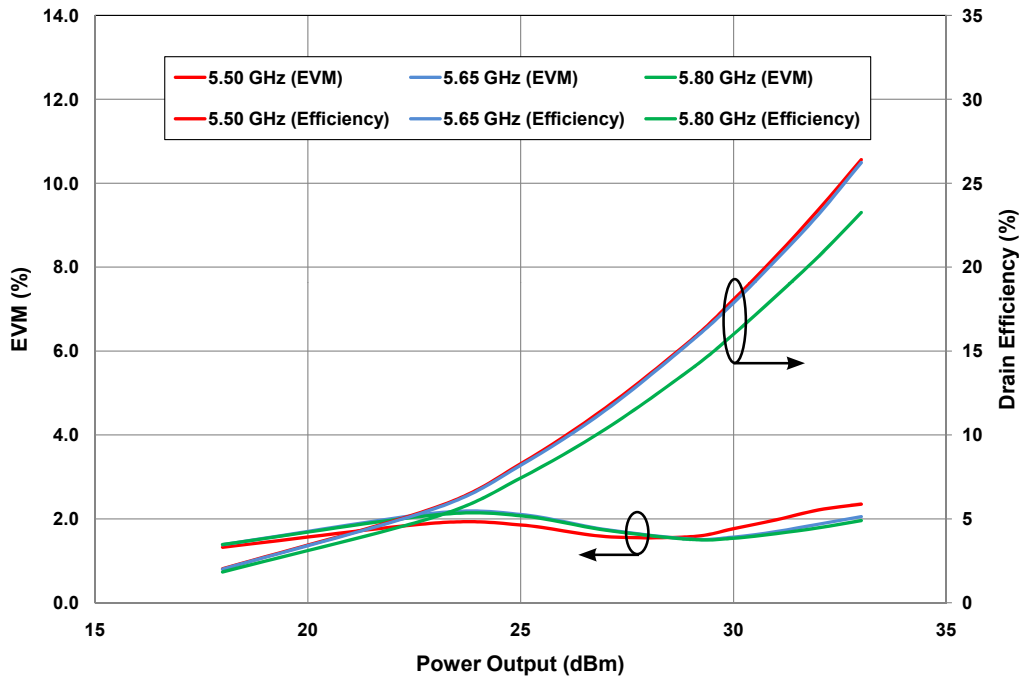
Note:
 Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

Typical WiMAX Performance

Drain Efficiency and Gain vs Power Output of the CGH55015 in the CGH55015-TB
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 115\text{ mA}$, 802.16-2004 OFDM, PAR = 9.8 dB



Typical EVM and Drain Efficiency vs Output Power of CGH55015 in the CGH55015-TB at 5.50 GHz, 5.65 GHz, 5.80 GHz, 802.16-2004 OFDM, PAR=9.8 dB

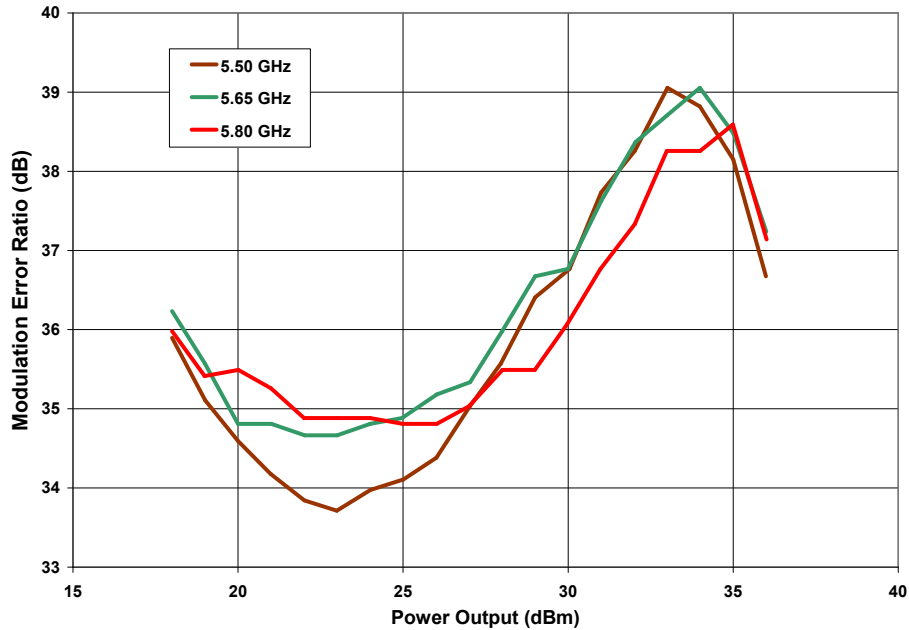


Note:

Under 802.16 OFDM, 3.5 MHz Channel BW, 1/4 Cyclic Prefix, 64 QAM Modulated Burst, Symbol Length of 59, Coding Type RS-CC, Coding Rate Type 2/3, PAR = 9.8 dB @ 0.01 % Probability on CCDF.

Typical DOCSIS Performance

DOCSIS Modulation Error Ratio vs Output Power of CGH55015

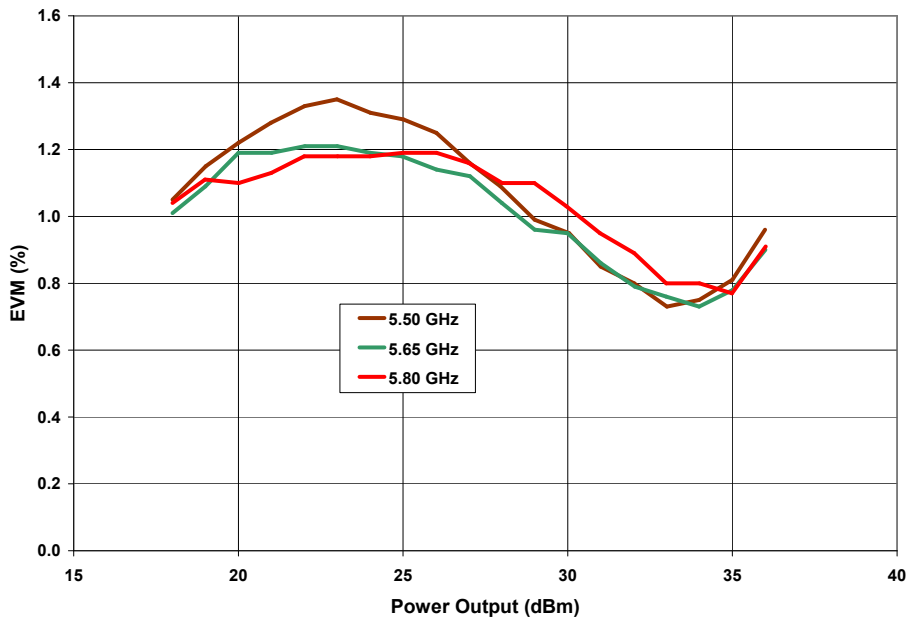


Note:

MER is the metric of choice for cable systems and can be related to EVM by the following equation:

$$EVM(\%) = 100 \times 10^{-((MER_{dB} + MTA_{dB})/20)}$$
 MTA is the "maximum-to-average constellation power ratio" which varies with the modulation type: MTA = 0 for BPSK and QPSK; 2.55 for 16QAM and 8QAM-DS; 3.68 for 64QAM and 32QAM-DS; 4.23 for 256QAM and 128QAM-DS

DOCSIS EVM vs Output Power of CGH55015 in Broadband Amplifier Circuit

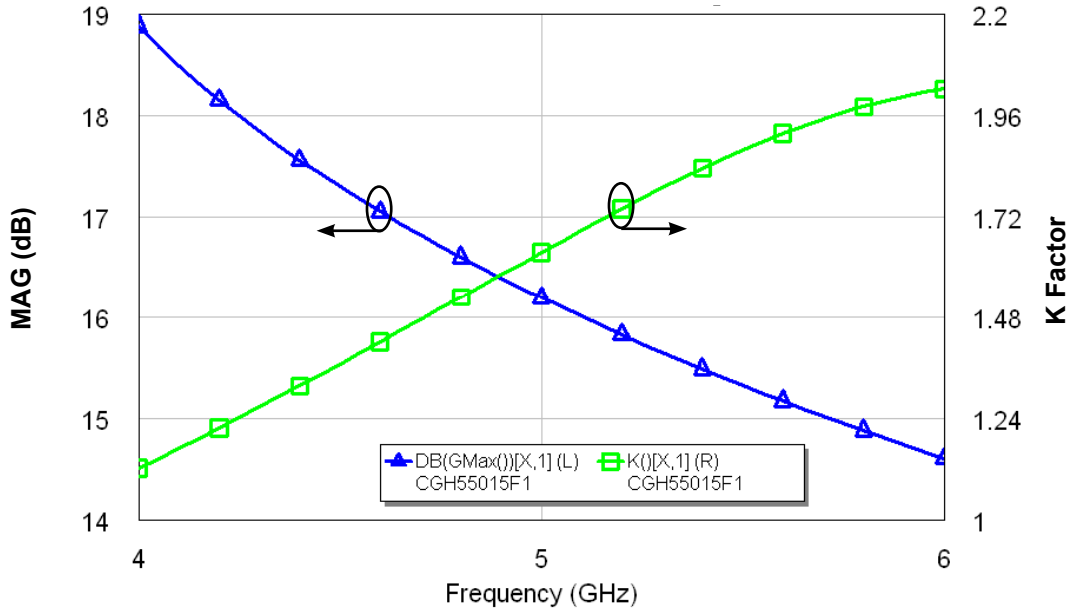


Note:

Under DOCSIS, 6.0 MHz Channel BW, 64 QAM, PN23, Filter Alpha 0.18, PAR = 6.7dB.

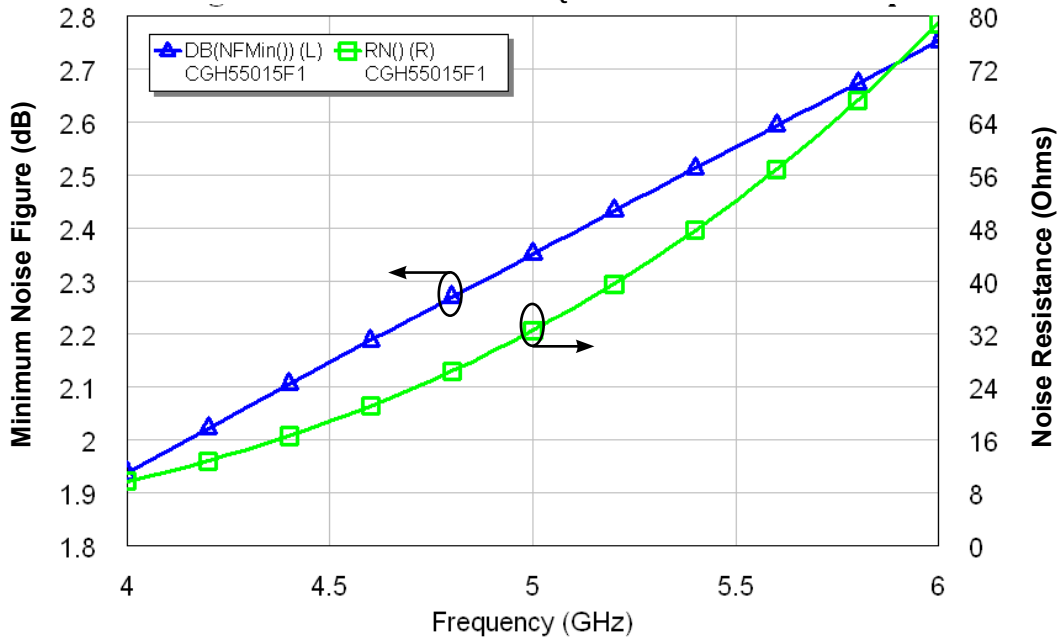
Typical Performance

Simulated Maximum Available Gain and K Factor of the CGH55015F1/P1
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 115\text{ mA}$

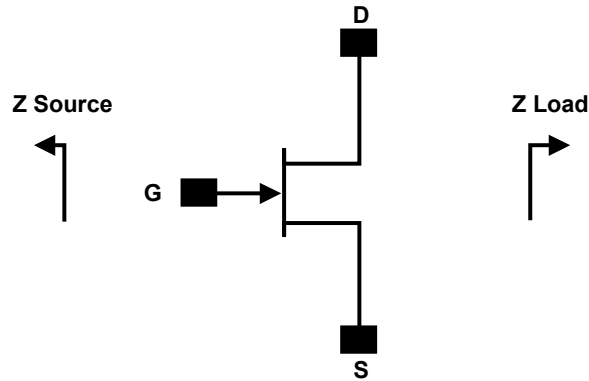


Typical Noise Performance

Simulated Minimum Noise Figure and Noise Resistance vs Frequency of the CGH55015F1/P1
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 115\text{ mA}$



Source and Load Impedances



| Frequency (MHz) | Z Source | Z Load |
|-----------------|--------------|-------------|
| 5500 | 8.7 - j30.2 | 21.6 - j4.7 |
| 5650 | 10.2 - j26.9 | 24.2 - j5.5 |
| 5800 | 12.3 - j24.3 | 26.5 - j7.5 |

Note 1. $V_{DD} = 28V$, $I_{DQ} = 115\text{ mA}$ in the 440166 package.

Note 2. Impedances are extracted from the CGH55015-TB demonstration amplifier and are not source and load pull data derived from the transistor.

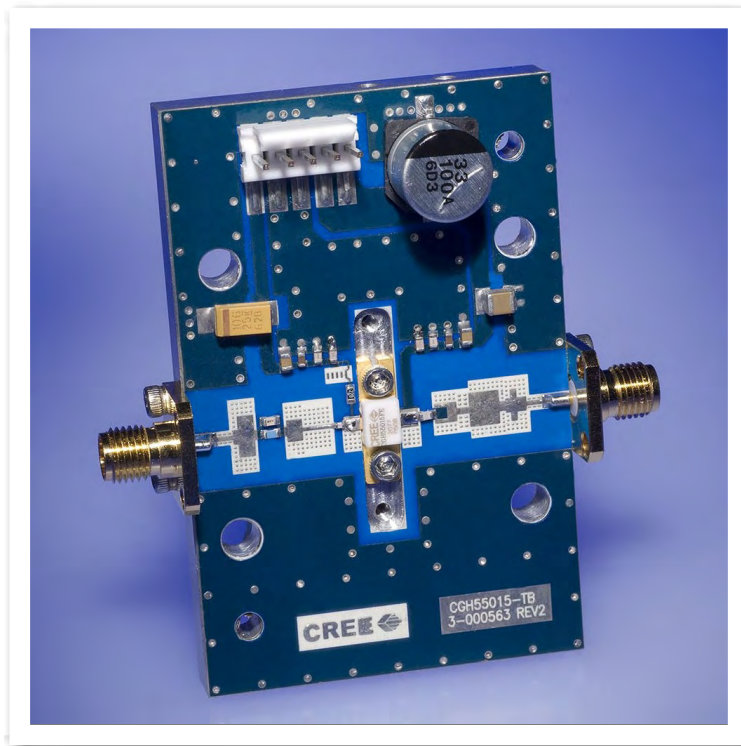
Electrostatic Discharge (ESD) Classifications

| Parameter | Symbol | Class | Test Methodology |
|---------------------|--------|------------|---------------------|
| Human Body Model | HBM | 1A > 250 V | JEDEC JESD22 A114-D |
| Charge Device Model | CDM | 1 < 200 V | JEDEC JESD22 C101-C |

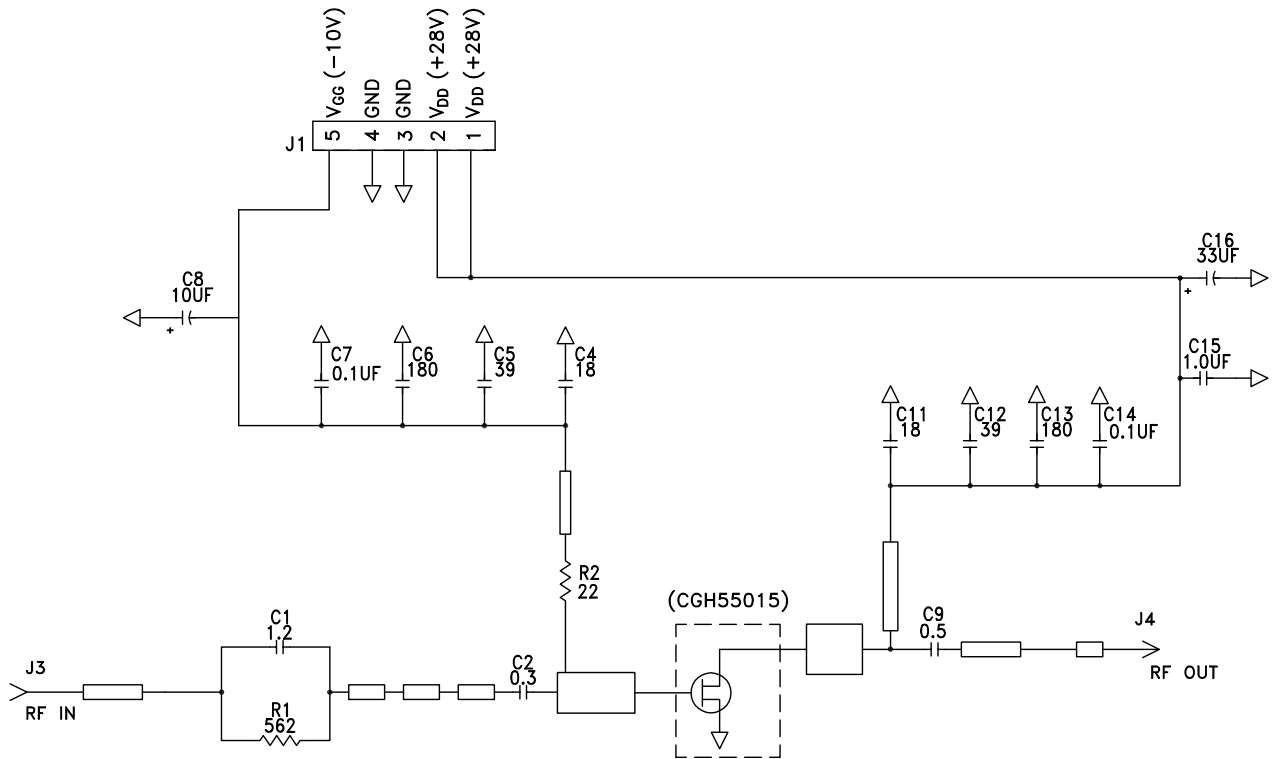
CGH55015-TB Demonstration Amplifier Circuit Bill of Materials

| Designator | Description | Qty |
|------------|---|-----|
| C1 | CAP, 1.2pF, +/-0.1 pF, 0603, ATC 600S | 1 |
| C2 | CAP, 0.3pF, +/-0.05 pF, 0402, ATC 600L | 1 |
| C9 | CAP, 0.5pF, +/-0.05pF, 0603, ATC 600S | 1 |
| C4,C11 | CAP, 18pF, +/-5%, 0603, ATC 600S | 2 |
| C5,C12 | CAP, 39pF +/-5%, 0603, ATC 600S | 2 |
| C6,C13 | CAP, CER, 180pF, 50V, +/-5%, COG, 0603 | 2 |
| C7,C14 | CAP, CER, 0.1UF, 50V, +/-10%, X7R, 0805 | 2 |
| C8 | CAP, 10UF, 16V, SMT, TANTALUM | 1 |
| C15 | CAP, 1.0UF ±10%, 100V, 1210, X7R | 1 |
| C16 | CAP, 33UF, 100V, ELECT, FK, SMD | 1 |
| R1 | RES, 1/16W, 0603, 1%, 562 OHMS | 1 |
| R2 | RES, 1/16W, 0603, 1%, 22 OHMS | 1 |
| J1 | HEADER RT> PLZ .1 CEN LK 5 POS | 1 |
| J3,J4 | CONN, SMA, FLANGE | 2 |
| - | PCB, RO4350B, Er = 3.48, h = 20 mil | 1 |
| - | CGH55015 | 1 |

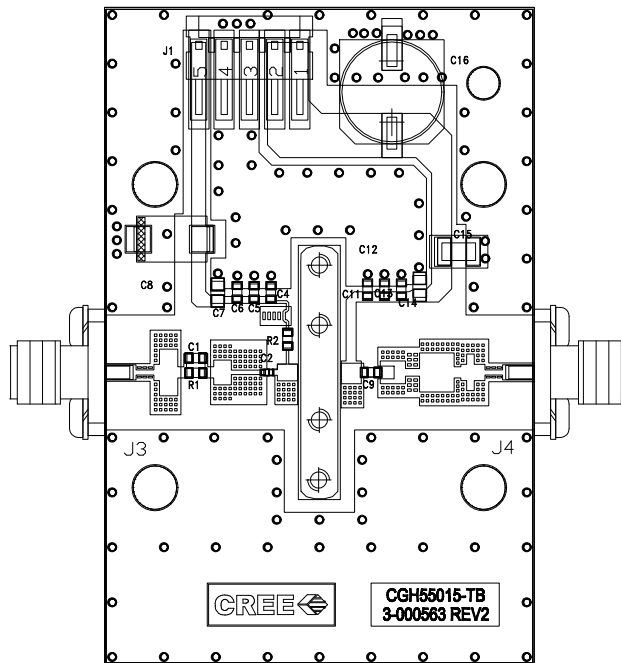
CGH55015-TB Demonstration Amplifier Circuit



CGH55015-TB Demonstration Amplifier Circuit Schematic



CGH55015-TB Demonstration Amplifier Circuit Outline



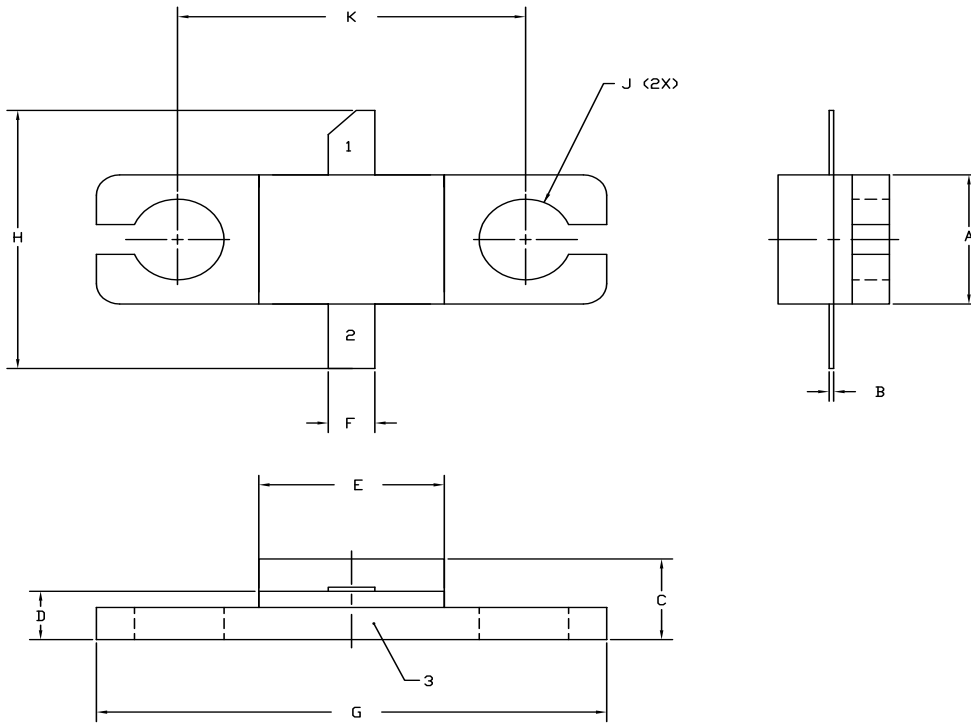


Typical Package S-Parameters for CGH55015
(Small Signal, $V_{DS} = 28\text{ V}$, $I_{DQ} = 115\text{ mA}$, angle in degrees)

| Frequency | Mag S11 | Ang S11 | Mag S21 | Ang S21 | Mag S12 | Ang S12 | Mag S22 | Ang S22 |
|-----------|---------|---------|---------|---------|---------|---------|---------|---------|
| 500 MHz | 0.909 | -125.16 | 17.56 | 107.52 | 0.026 | 20.86 | 0.330 | -95.81 |
| 600 MHz | 0.903 | -134.72 | 15.15 | 101.24 | 0.027 | 15.25 | 0.318 | -103.71 |
| 700 MHz | 0.898 | -142.24 | 13.28 | 95.96 | 0.027 | 10.66 | 0.312 | -109.87 |
| 800 MHz | 0.895 | -148.34 | 11.79 | 91.38 | 0.027 | 6.76 | 0.309 | -114.77 |
| 900 MHz | 0.893 | -153.43 | 10.58 | 87.30 | 0.028 | 3.37 | 0.310 | -118.75 |
| 1.0 GHz | 0.891 | -157.78 | 9.59 | 83.58 | 0.028 | 0.34 | 0.312 | -122.07 |
| 1.2 GHz | 0.889 | -164.93 | 8.06 | 76.89 | 0.028 | -4.92 | 0.320 | -127.35 |
| 1.4 GHz | 0.888 | -170.72 | 6.94 | 70.90 | 0.027 | -9.46 | 0.332 | -131.53 |
| 1.6 GHz | 0.888 | -175.64 | 6.08 | 65.34 | 0.027 | -13.51 | 0.347 | -135.09 |
| 1.8 GHz | 0.888 | -179.99 | 5.41 | 60.10 | 0.027 | -17.20 | 0.362 | -138.30 |
| 2.0 GHz | 0.889 | 176.04 | 4.86 | 55.09 | 0.026 | -20.60 | 0.378 | -141.33 |
| 2.2 GHz | 0.889 | 172.35 | 4.42 | 50.24 | 0.025 | -23.76 | 0.394 | -144.27 |
| 2.4 GHz | 0.890 | 168.84 | 4.05 | 45.53 | 0.025 | -26.70 | 0.410 | -147.16 |
| 2.6 GHz | 0.891 | 165.46 | 3.73 | 40.93 | 0.024 | -29.44 | 0.426 | -150.04 |
| 2.8 GHz | 0.891 | 162.16 | 3.46 | 36.41 | 0.024 | -31.97 | 0.441 | -152.92 |
| 3.0 GHz | 0.892 | 158.90 | 3.23 | 31.95 | 0.023 | -34.32 | 0.455 | -155.81 |
| 3.2 GHz | 0.893 | 155.67 | 3.03 | 27.55 | 0.022 | -36.45 | 0.469 | -158.73 |
| 3.4 GHz | 0.893 | 152.43 | 2.85 | 23.19 | 0.021 | -38.38 | 0.482 | -161.68 |
| 3.6 GHz | 0.894 | 149.18 | 2.70 | 18.85 | 0.021 | -40.07 | 0.494 | -164.66 |
| 3.8 GHz | 0.894 | 145.89 | 2.56 | 14.53 | 0.020 | -41.52 | 0.506 | -167.68 |
| 4.0 GHz | 0.894 | 142.54 | 2.44 | 10.22 | 0.019 | -42.71 | 0.516 | -170.74 |
| 4.1 GHz | 0.895 | 140.85 | 2.38 | 8.07 | 0.019 | -43.19 | 0.521 | -172.29 |
| 4.2 GHz | 0.895 | 139.14 | 2.33 | 5.91 | 0.019 | -43.59 | 0.526 | -173.85 |
| 4.3 GHz | 0.895 | 137.40 | 2.28 | 3.75 | 0.018 | -43.92 | 0.530 | -175.43 |
| 4.4 GHz | 0.895 | 135.65 | 2.23 | 1.58 | 0.018 | -44.16 | 0.535 | -177.02 |
| 4.5 GHz | 0.895 | 133.88 | 2.18 | -0.59 | 0.018 | -44.32 | 0.539 | -178.62 |
| 4.6 GHz | 0.895 | 132.08 | 2.14 | -2.77 | 0.017 | -44.38 | 0.543 | 179.75 |
| 4.7 GHz | 0.895 | 130.26 | 2.10 | -4.96 | 0.017 | -44.35 | 0.546 | 178.11 |
| 4.8 GHz | 0.895 | 128.41 | 2.06 | -7.15 | 0.017 | -44.23 | 0.550 | 176.45 |
| 4.9 GHz | 0.895 | 126.53 | 2.03 | -9.36 | 0.017 | -44.02 | 0.553 | 174.77 |
| 5.0 GHz | 0.895 | 124.63 | 1.99 | -11.58 | 0.016 | -43.71 | 0.556 | 173.07 |
| 5.1 GHz | 0.895 | 122.69 | 1.96 | -13.81 | 0.016 | -43.30 | 0.559 | 171.35 |
| 5.2 GHz | 0.895 | 120.72 | 1.93 | -16.05 | 0.016 | -42.81 | 0.561 | 169.60 |
| 5.3 GHz | 0.895 | 118.73 | 1.90 | -18.31 | 0.016 | -42.22 | 0.564 | 167.83 |
| 5.4 GHz | 0.895 | 116.70 | 1.87 | -20.59 | 0.016 | -41.56 | 0.566 | 166.04 |
| 5.5 GHz | 0.895 | 114.63 | 1.84 | -22.89 | 0.016 | -40.83 | 0.568 | 164.21 |
| 5.6 GHz | 0.895 | 112.53 | 1.81 | -25.20 | 0.016 | -40.05 | 0.570 | 162.36 |
| 5.7 GHz | 0.895 | 110.39 | 1.79 | -27.53 | 0.016 | -39.22 | 0.572 | 160.47 |
| 5.8 GHz | 0.895 | 108.22 | 1.77 | -29.89 | 0.016 | -38.35 | 0.574 | 158.55 |
| 5.9 GHz | 0.895 | 106.00 | 1.74 | -32.27 | 0.016 | -37.48 | 0.575 | 156.60 |
| 6.0 GHz | 0.895 | 103.75 | 1.72 | -34.67 | 0.016 | -36.62 | 0.576 | 154.61 |

Download this s-parameter file in ".s2p" format at http://www.cree.com/products/wireless_s-parameters.asp

Product Dimensions CGH55015F1 (Package Type — 440166)



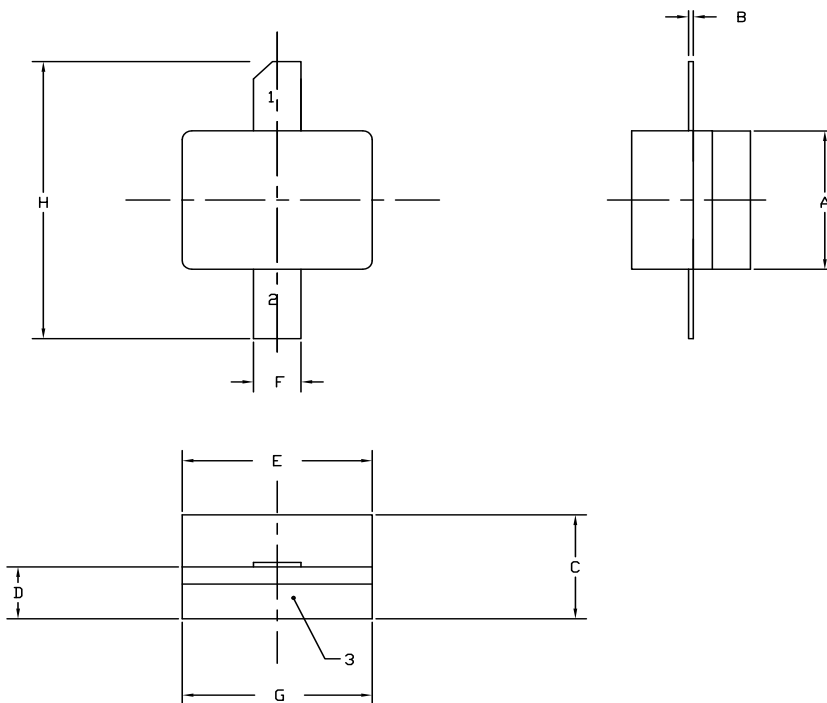
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
4. LID MAY BE MISALIGNED TO THE BODY OF THE PACKAGE BY A MAXIMUM OF 0.008" IN ANY DIRECTION.
5. ALL PLATED SURFACES ARE NI/AU

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.155 | 0.165 | 3.94 | 4.19 |
| B | 0.004 | 0.006 | 0.10 | 0.15 |
| C | 0.115 | 0.135 | 2.92 | 3.43 |
| D | 0.057 | 0.067 | 1.45 | 1.70 |
| E | 0.195 | 0.205 | 4.95 | 5.21 |
| F | 0.045 | 0.055 | 1.14 | 1.40 |
| G | 0.545 | 0.555 | 13.84 | 14.09 |
| H | 0.280 | 0.360 | 7.11 | 9.14 |
| J | Ø .100 | | 2.54 | |
| K | 0.375 | | 9.53 | |

PIN 1. GATE
 PIN 2. DRAIN
 PIN 3. SOURCE

Product Dimensions CGH55015P1 (Package Type — 440196)



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ADHESIVE FROM LID MAY EXTEND A MAXIMUM OF 0.020" BEYOND EDGE OF LID.
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5. ALL PLATED SURFACES ARE NI/AU

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|------|
| | MIN | MAX | MIN | MAX |
| A | 0.155 | 0.165 | 3.94 | 4.19 |
| B | 0.003 | 0.006 | 0.10 | 0.15 |
| C | 0.115 | 0.135 | 2.92 | 3.17 |
| D | 0.057 | 0.067 | 1.45 | 1.70 |
| E | 0.195 | 0.205 | 4.95 | 5.21 |
| F | 0.045 | 0.055 | 1.14 | 1.40 |
| G | 0.195 | 0.205 | 4.95 | 5.21 |
| H | 0.280 | 0.360 | 7.11 | 9.14 |

PIN 1. GATE
 PIN 2. DRAIN
 PIN 3. SOURCE



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Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

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- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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